Probe Cleaning

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Southwest Test Workshop

San Diego, California
June 1998





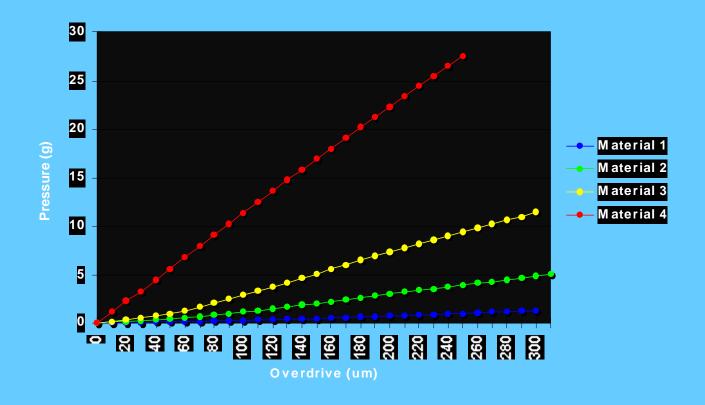
Agenda

Problem Statement
Methods of Cleaning
Engineering Results
What's next?
Summary





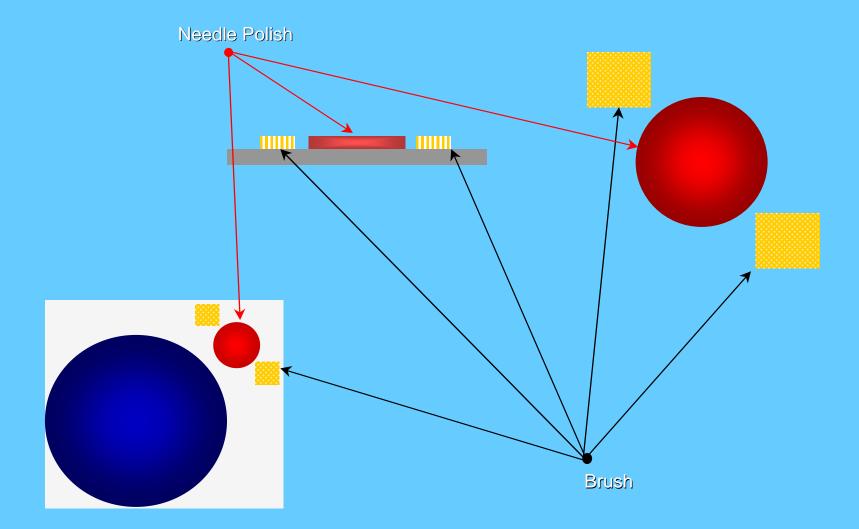
Effect of cleaning material elasticity on total probe force







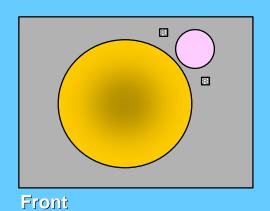
Needle Polish and Brush cleaning

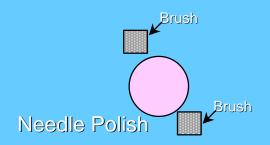


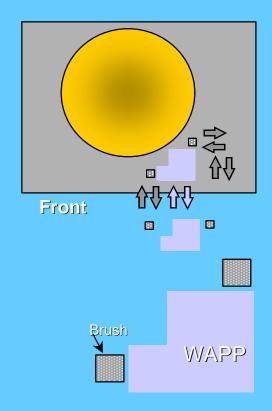




Various cleaning options









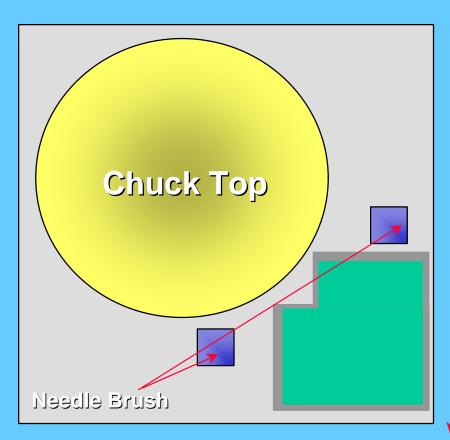
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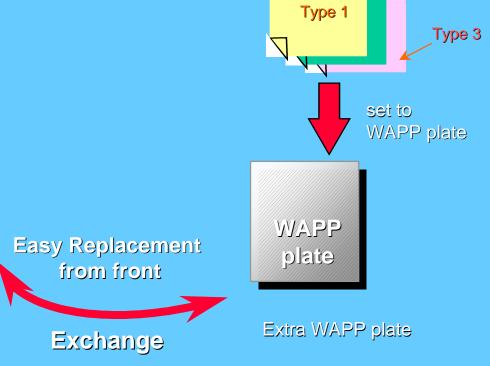


Wide Area Polish Plate

Size, Exchangeable, Effective



WAPP has separate Z drive motion from chuck



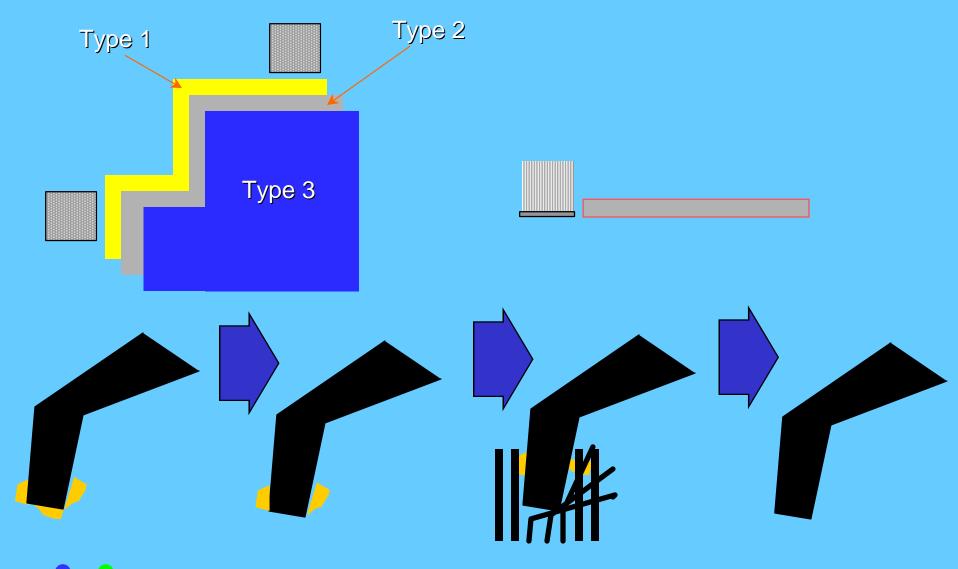




Type 2

Cleaning Materials

Abrasive and Brush cleaning

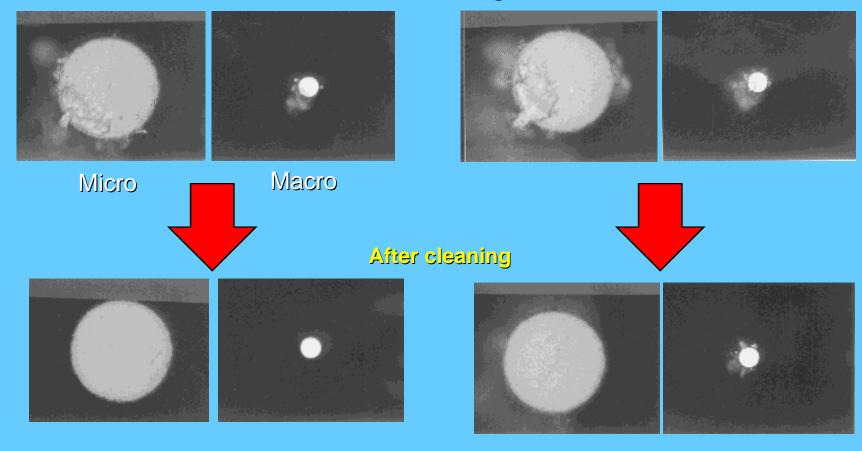






The coexistence of the Type 2 cleaning material and brush

Before cleaning



Type 2 Material and brush

Test System Division

Type 2 Material

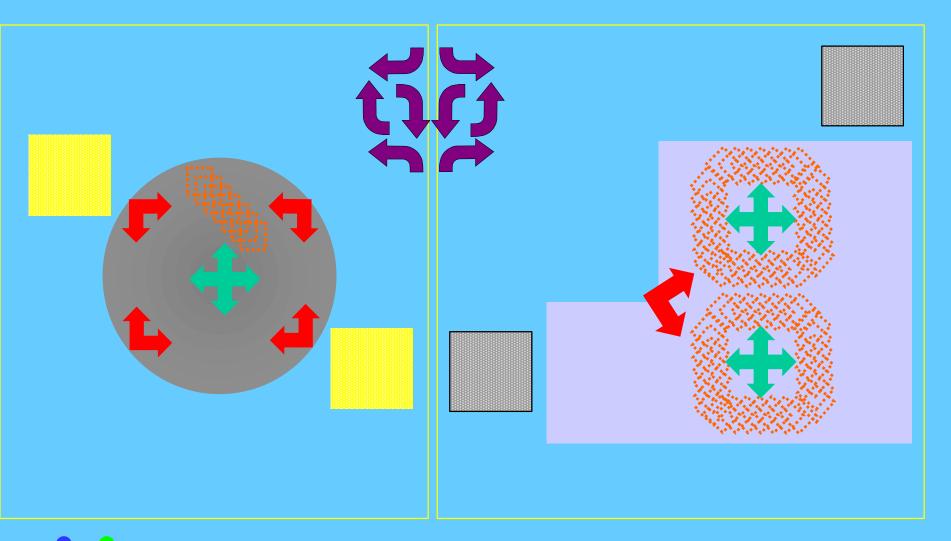


Results of soft cleaner Type 3 and Brush Cleaning





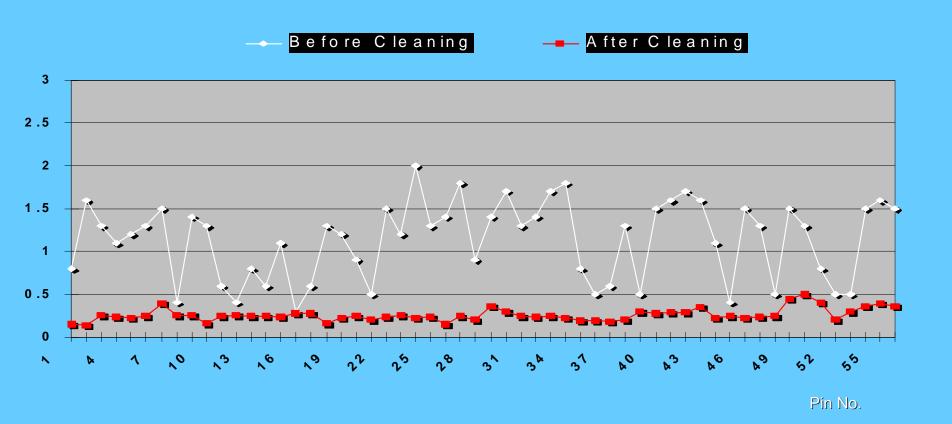
Cleaning patterns







Contact resistance before/after Needle Polish and Brush cleaning







WAPP

Exchange from SACC cover (front of prober)







Exchange WAPP plate from front of prober anytime during testing. Without undocking test head No planarity adjustment required.

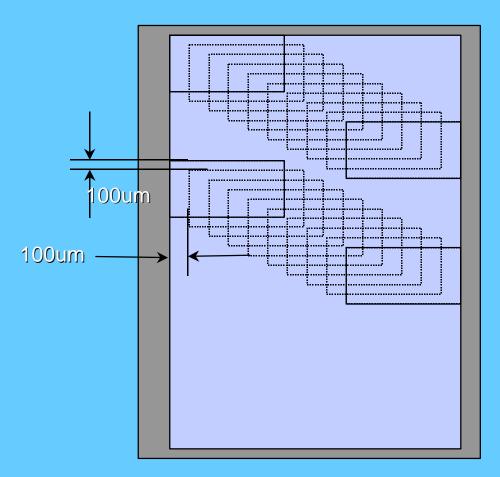






Life of Cleaning Pad

600 Probes Array



600X4 =2400 Contacts

2400/20x200/15

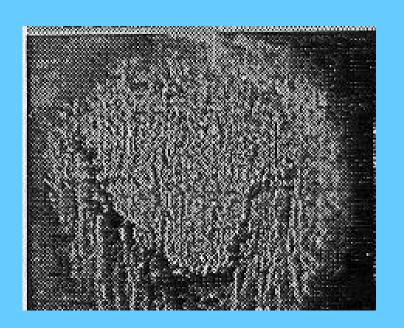
= 800

Available < 800dies/wafer

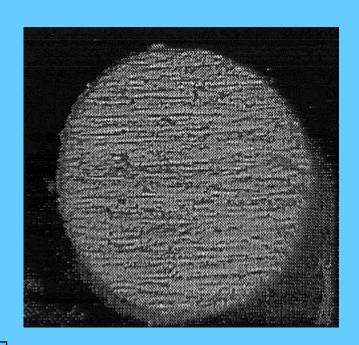




Tip Cleaning with Type 3 abrasive and Brush







Before

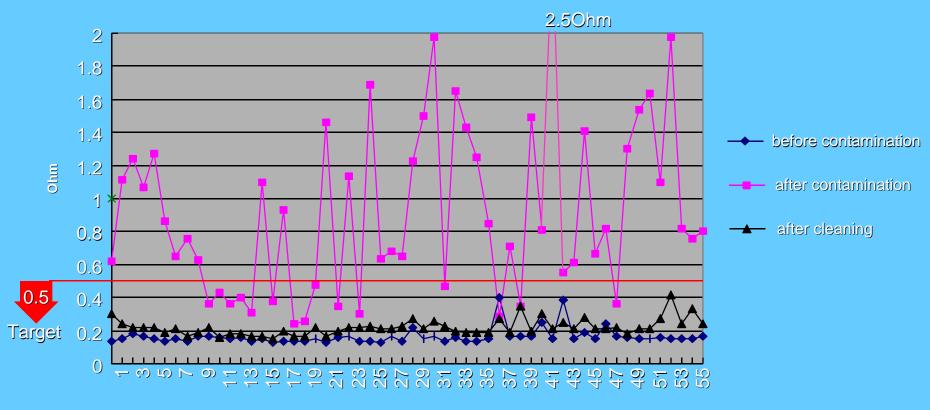
X Y motion

After





Contact resistance before/after Type 3 abrasive and brush cleaning



Pin Number



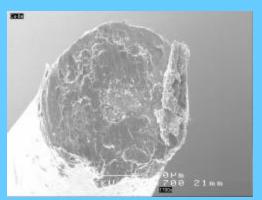


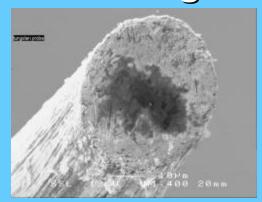
What's next?

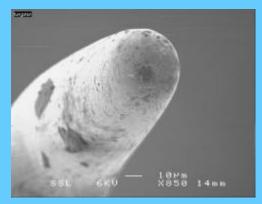




Probe tips before/after nonabrasive cleaning



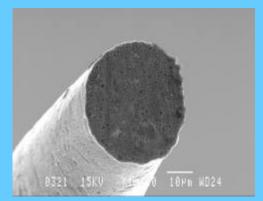


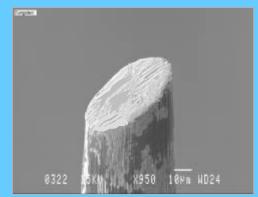


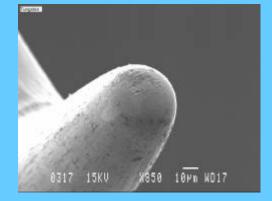








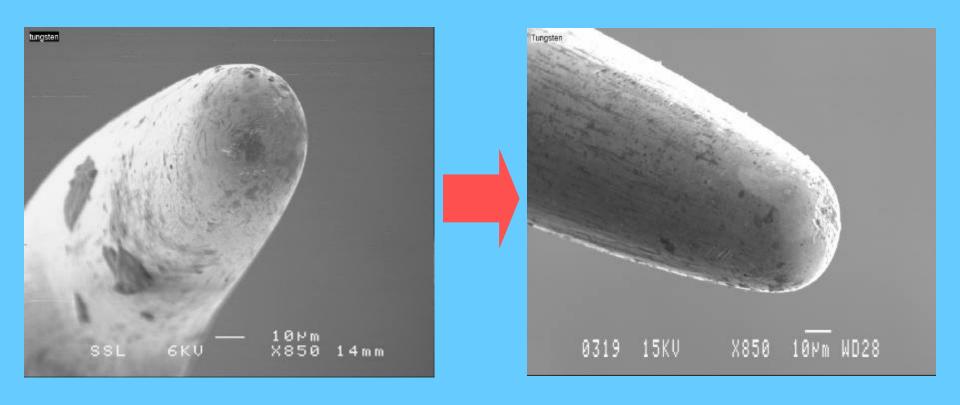








Probe tip after nonabrasive cleaning







Contact resistance before/after nonabrasive cleaning

